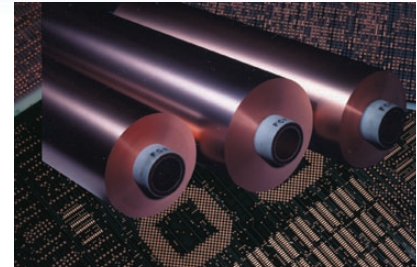


# F-DP for Package, Substrate and Multilayer Board

- This foil is used for mass-production of cellular phones.
- Trial mass production of the next generation package is underway.



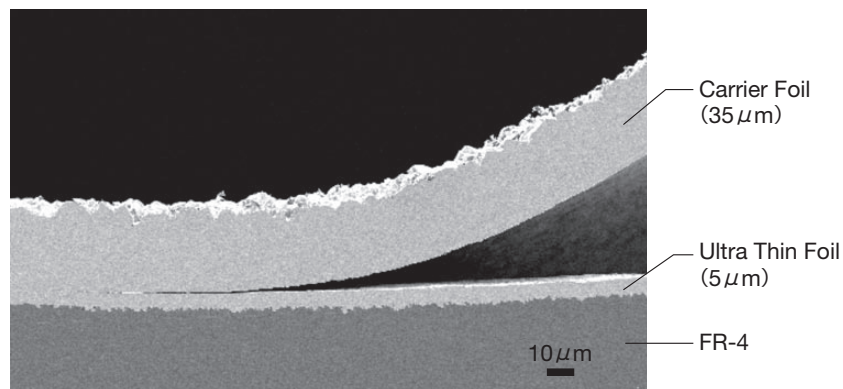
## Product

- F-DP (surface foil / carrier foil thickness: 3 / 35, 5 / 35, 9 / 70  $\mu\text{m}$ )

## Features

- Stable carrier peeling strength prevents peeling-off of the carrier foil during production processes.
- Uniform product quality such as high and stabilized peeling strength.

## Cross-sectional Structure



## Typical Properties

	Carrier Peel Strength (kN/m)	Treated Side Roughness ( $\mu\text{m}$ )		Peel Strength (vs. FR-4) (kN/m)
		Ra	Rz	
3 / 35	0.03	0.4	3.5	1.3
5 / 35	0.03	0.4	3.5	1.4
9 / 70	0.03	0.7	4.5	1.4

(Note 1) Carrier Peel Strength: measured after 170°C × 1hr pressing on FR-4 substrate.

(Note 2) Peel Strength (vs. FR-4) : measured after 35 $\mu\text{m}$  thick plating followed by 170°C × 1hr pressing.